

Amended  
B2

wherein a connection hole is provided for connecting the first conductive layer to the second conductive layer, and  
wherein the connection hole extends into the semiconductor substrate, and  
wherein a contact layer is provided in the connection hole.

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B3

7. (Amended) A semiconductor device comprising:  
a semiconductor substrate having a contact region provided therein;  
an insulation layer provided above the semiconductor substrate; and  
a semiconductor layer provided above the insulation layer, wherein the semiconductor layer includes an element isolation region which has a connection hole;  
a conductive layer provided above the semiconductor layer or in the semiconductor layer, and has a function of allowing charge to flow into the semiconductor substrate, the contact region being electrically connected to the conductive layer; and  
a contact layer provided in the connection hole, the contact layer electrically connecting the contact region and the conductive layer.
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